

Title (en)

METHOD FOR TRANSFER MOLDING STANDARD ELECTRONIC PACKAGES AND APPARATUS FORMED THEREBY

Title (de)

VERFAHREN ZUM TRANSFERGIESSEN VON ELEKTRONISCHEN STANDARDTEILEN UND SO GEFORMTESGERÄT

Title (fr)

PROCEDE DE MOULAGE PAR TRANSFERT DES MODULES ELECTRONIQUES STANDARD ET APPAREIL AINSI FORME

Publication

**EP 0954425 A1 19991110 (EN)**

Application

**EP 97948154 A 19971113**

Priority

US 9719980 W 19971113

IPC 1-7

**B29C 45/02**; **H01L 23/02**; **H01L 23/495**

IPC 8 full level

**B29C 45/02** (2006.01); **B42D 15/10** (2006.01); **G06K 19/077** (2006.01); **H01L 21/56** (2006.01); **H01L 23/02** (2006.01); **H01L 23/495** (2006.01); **H05K 13/00** (2006.01)

Designated contracting state (EPC)

DE FR GB IT

DOCDB simple family (publication)

AU 5427898 A 19990607; EP 0954425 A1 19991110; EP 0954425 A4 20010822; JP 2001509321 A 20010710

DOCDB simple family (application)

AU 5427898 A 19971113; EP 97948154 A 19971113; JP 52835499 A 19971113